## WHAT IS CLAIMED IS:

1. A semiconductor memory system comprising:

a memory controller;

N system data buses connected to the memory controller, each of the N system data buses having a width of M/N bits, where M is a natural number and N is a natural number of at least 2; and

first through *P*-th memory module groups, each of the first through *P*-th memory module groups having *N* memory modules, where *P* is a natural number;

wherein the *N* memory modules within each of the first through *P*-th memory module groups are connected to a respectively different one of the *N* system data buses, and wherein the first through *P*-th memory module groups are operated in response to respective first through *P*-th chip select signals.

- 2. The system of claim 1, wherein *M* is a bit-width of an entire system data bus of the semiconductor memory system.
- 3. The system of claim 1, wherein the *N* system data buses are wired such that data transmission times are the same from the *N* memory modules within each of the first through *P*-th module groups to the memory controller.
- 4. The system of claim 1, wherein each of the *N* memory modules includes *L* memory devices, wherein each of the *L* memory devices is divided into *N* banks, and wherein the *N* banks of each of the *L* memory devices share a data bus of *M*/*N* bits and are separately operated in response to the first through *P*-th chip select signals.
- 5. The system of claim 4, wherein the first through *P*-th chip select signals are respectively applied to the *N* banks.
- 6. The system of claim 4, wherein each of the *L* memory devices has a data bus width of *M/L* bits.

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- 7. The system of claim 1, wherein each of the N memory modules includes L memory devices, and wherein each of the L memory devices has a bus width of  $M/(N^*L)$  bits.
  - 8. A semiconductor memory system comprising: a memory controller;

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N system data buses connected to the memory controller, each of the N system data buses having a width of M/N bits, where M is a natural number and N is a natural number of at least 2;

a first memory module group having *N* memory modules respectively connected to the *N* system data buses, wherein the *N* memory modules of the first memory module group each have a data bus width of *M/N* bits and are operated in response to first chip select signals; and

a second memory module group having at least one memory module connected to all of the *N* system data buses, wherein the at least one memory module of the second memory module group has a data bus width of M bits and is operated in response to a second chip select signal.

- 9. The system of claim 8, wherein *M* is a bit-width of an entire system data bus of the semiconductor memory system.
- 10. The system of claim 8, wherein the *N* system data buses are wired such that data transmission times are the same from the memory modules of the first memory module group to the memory controller.
- 11. The system of claim 8, wherein each of the memory modules of the first memory module group includes L memory devices, wherein the L memory devices are divided into N banks, wherein the N banks of each of the L memory devices share a data bus of M/N bits and are separately operated in response to the first chip select signals.

12. The system of claim 11, wherein the first chip select signals are respectively applied to the *N* banks.

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- 13. The system of claim 11, wherein each of the L memory devices has a data bus width of M/L bits.
- 14. The system of claim 8, wherein each of the memory modules includes L memory devices, and each of the L memory devices has a bus width of  $M/(N^*L)$  bits.

15. A semiconductor memory system, the system comprising: a memory controller;

N system data buses connected to the memory controller, each of the N system data buses including a plurality of data buffers and having a width of M/N bits, where M is a natural number and N is a natural number of at least 2; and

first through *P*-th memory module groups connected to the *N* system data buses, each of the first through *P*-th memory module groups having *N* memory modules:

wherein the *N* memory modules within each of the first through *P*-th memory module groups are connected to the data buffers of respectively different ones of the *N* system data buses, wherein the first through *P*-th memory module groups are operated in response to respective first through *P*-th chip select signals.

- 16. The system of claim 15, wherein *M* is a bit-width of an entire system data bus of the semiconductor memory system.
- 17. The system of claim 15, wherein, for each of the first through *P*-th module groups, the *N* system data buses are wired such that data transmission times are the same from the *N* memory modules within each of the first through *P*-th module groups to the memory controller.

- 18. The system of claim 15, The system of claim 8, wherein each of the memory modules of the first memory module group includes *L* memory devices, wherein the *L* memory devices are divided into *N* banks, wherein the *N* banks of each of the *L* memory devices share a data bus of *M*/*N* bits and are separately operated in response to chip select signals.
- 19. The system of claim 18, wherein the chip select signals are respectively applied to the *N* banks.

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- 20. The system of claim 18, wherein each of the L memory devices has a data bus width of M/L bits.
- 21. The system of claim 15, wherein each of the memory modules includes L memory devices, and each of the L memory devices has a bus width of  $M/(N^*L)$  bits.